

### General Description

The Sanrise SRT03N050L uses advanced split gate trench technology. It has extremely low on resistance, low gate charge and fast switching time. This device is ideal for high frequency switching and synchronous rectification.

The SRT03N050L break down voltage is 30V and it has a high rugged avalanche characteristics. The SRT03N050L is available in PDFN3.3\*3.3 package.

### Features

- $BV_{DSS} = 30V, I_D = 67A$
- Low On Resistance  
 $R_{DS(ON\_TYP)} = 4.1m\Omega @ V_{GS} = 10V.$   
 $R_{DS(ON\_TYP)} = 6.7m\Omega @ V_{GS} = 4.5V.$
- Ultra Low Gate Charge,  $Q_g=17.4nC$  typ.
- Fast switching capability
- Robust design with better EAS performance
- 100% UIS Tested

### Application

- DC/DC Converters
- Synchronous Rectifier
- Power Switch
- Motor Driver
- BMS

### Symbol

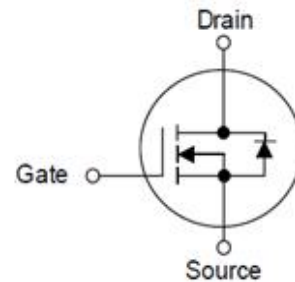


Figure 1 Symbol of SRT03N050L

### Package Type

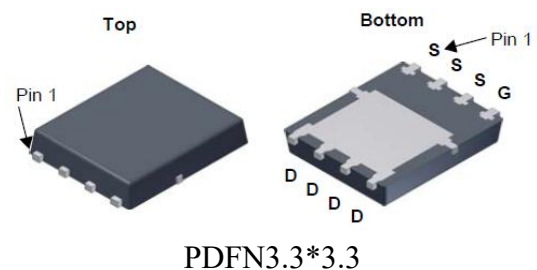
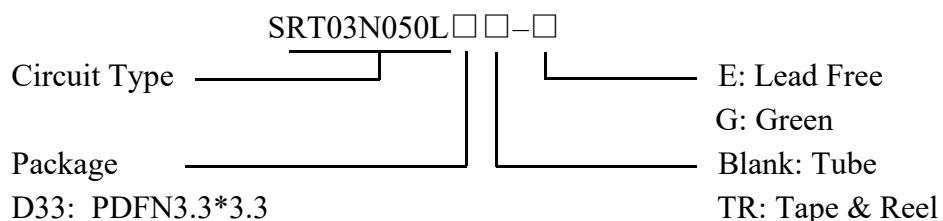


Figure 2 Package Type of SRT03N050L

### Ordering Information



Package	Part Number	Marking ID	Packing Type
	Green	Green	
PDFN3.3*3.3	SRT03N050LD33TR-G	03N050LD33G	Tape&Reel

### Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DSS}$	30	V
Gate-Source Voltage	$V_{GSS}$	±20	V
Continuous Drain Current	$I_D$	67	A
Pulsed Drain Current <sup>(4)</sup>	$I_{DM}$	268	A
Avalanche Current <sup>(5)</sup>	$I_{AS}$	17	A
Single Pulse Avalanche Energy <sup>(5)</sup>	$E_{AS}$	29	mJ
Power Dissipation ( $T_C = 25^\circ\text{C}$ )	$P_D$	37	W
Operating Junction Temperature	$T_J$	150	°C
Storage Temperature	$T_{STG}$	-55 ~ 150	°C
Lead Temperature (Soldering, 10 sec)	$T_{LEAD}$	260	°C

Note:

1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Limited by package.
3. Rated according to  $R_{\theta JC}$ .
4. Limited by maximum  $T_J$ .
5.  $T_A = 25^\circ\text{C}$ ,  $L = 0.1\text{mH}$ ,  $I_{AS} = 17\text{A}$ .

### Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$			3.4	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$			62	

**Electrical Characteristics**

 T<sub>J</sub> = 25°C, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Statistic Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V			1	uA
Gate-Body Leakage Current	Forward	I <sub>GSSF</sub>	V <sub>GS</sub> =20V, V <sub>DS</sub> =0V		100	nA
	Reverse	I <sub>GSSR</sub>	V <sub>GS</sub> =-20V, V <sub>DS</sub> =0V		-100	nA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	1.0		2.0	V
Static Drain-Source On-Resistance	R <sub>D(S)ON</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =10A		4.1	5.0	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A		6.7	10.0	mΩ
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz		960		pF
Output Capacitance	C <sub>OSS</sub>			410		
Reverse Transfer Capacitance	C <sub>RSS</sub>			60		
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =20A R <sub>G</sub> =3.0Ω, V <sub>GS</sub> =10V		7		ns
Rise Time	t <sub>r</sub>			2.8		
Turn-off Delay Time	t <sub>d(off)</sub>			21.4		
Fall Time	t <sub>f</sub>			5.3		
<b>Gate Charge Characteristics</b>						
Gate to Source Charge	Q <sub>gs</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =20A V <sub>GS</sub> =0 to 10V		3.4		nC
Gate to Drain Charge	Q <sub>gd</sub>			3.1		
Gate Charge Total	Q <sub>g</sub>			17.4		
Gate Plateau Voltage	g <sub>fs</sub>	V <sub>DD</sub> =15V, I <sub>D</sub> =20A		85		S
<b>Reverse Diode Characteristics</b>						
Drain-Source Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>SD</sub> =10A		0.8		V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>GS</sub> =0V, I <sub>F</sub> =10A		12.3		ns
Reverse Recovery Charge	Q <sub>rr</sub>	dI <sub>F</sub> /dt=100A/us		17.6		nC

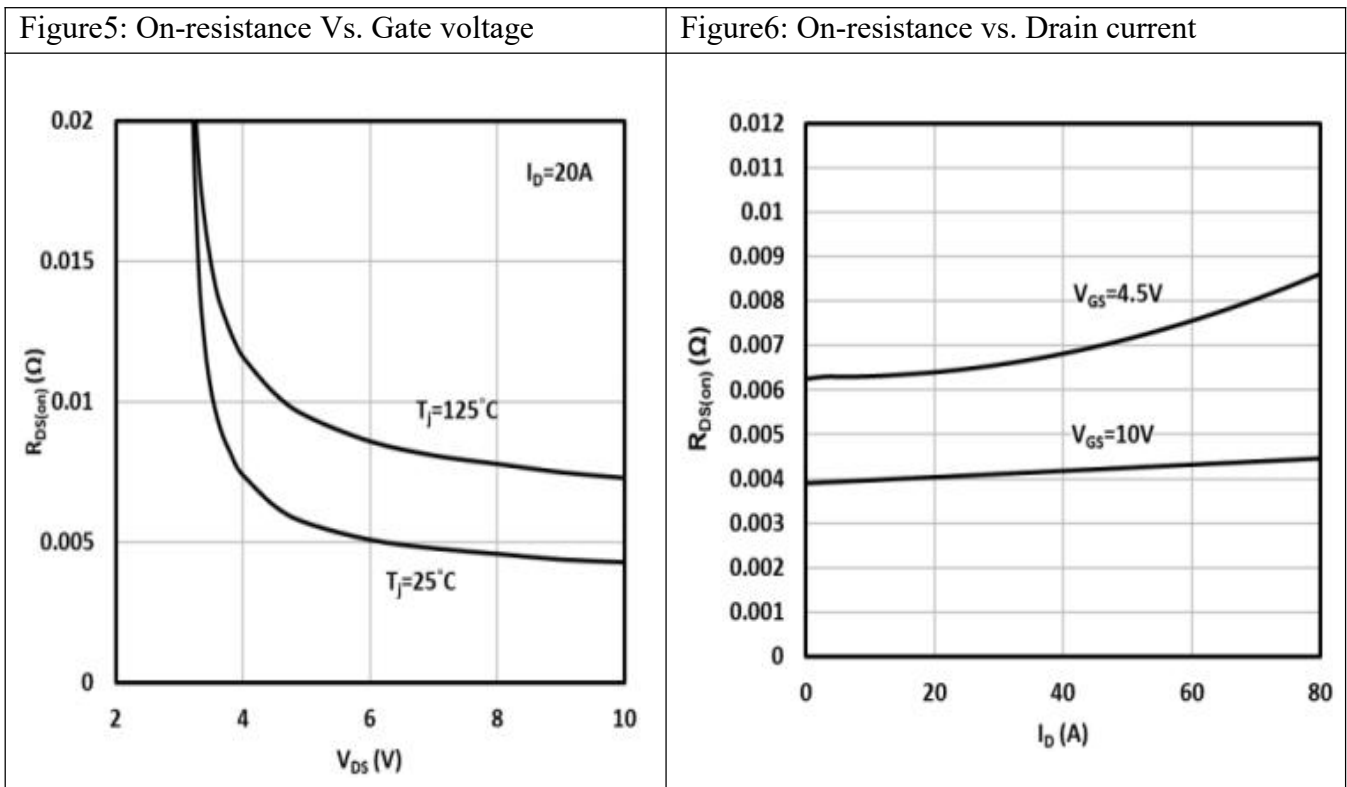
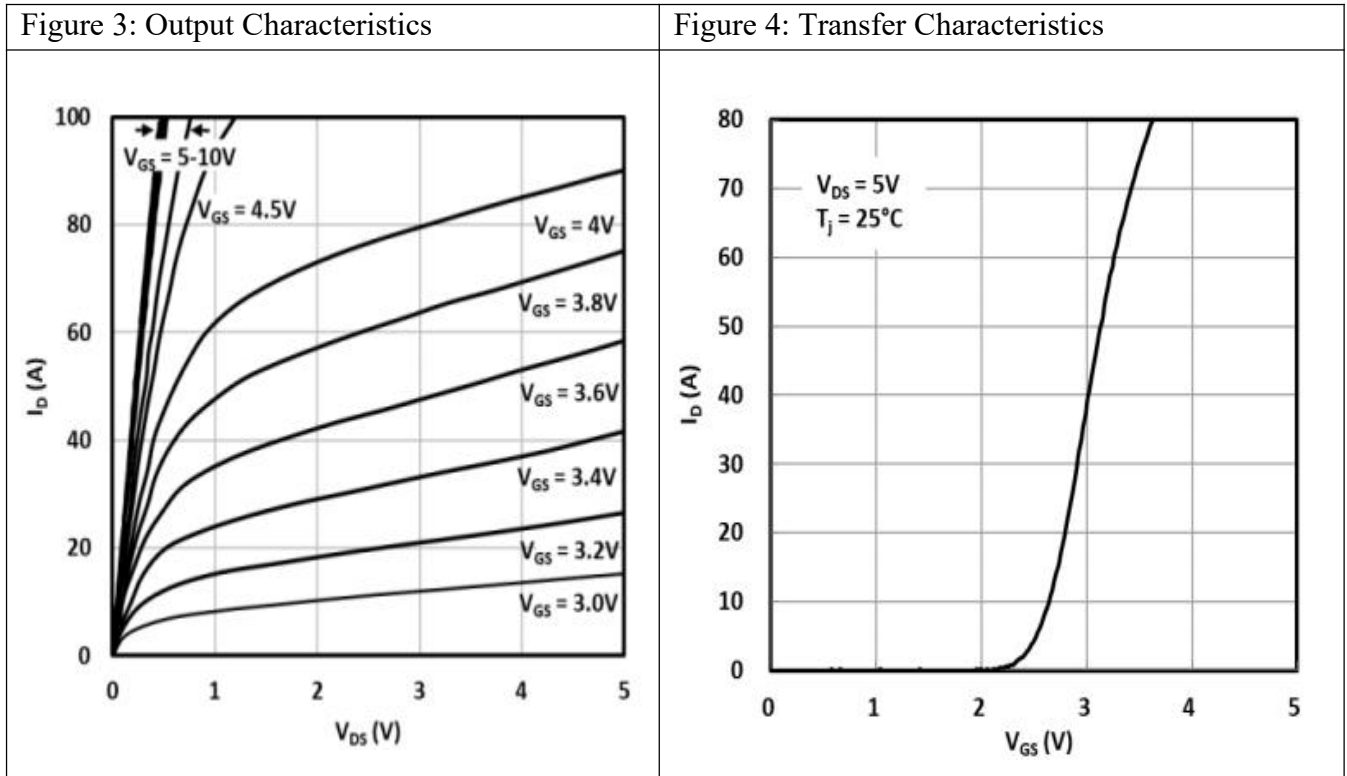
**Typical Performance Characteristics**


Figure 7: Source to drain diode forward Characteristics

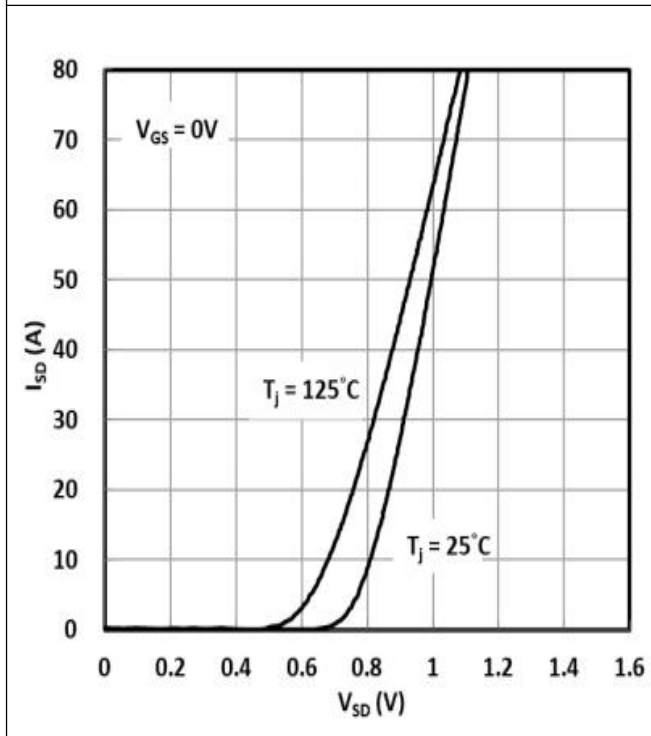


Figure 8: Capacitance vs. Drain-to-Source voltage

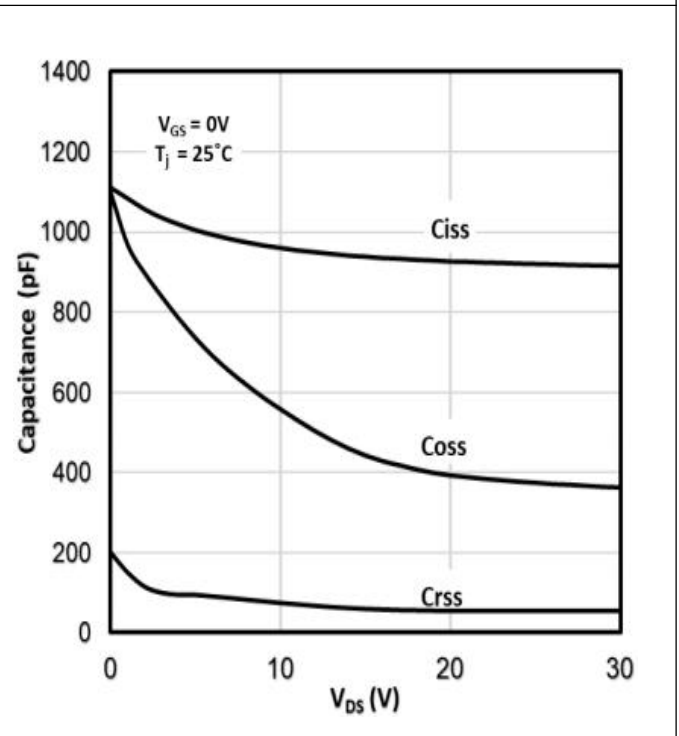


Figure 9: Gate-to-Source voltage vs. Gate charge

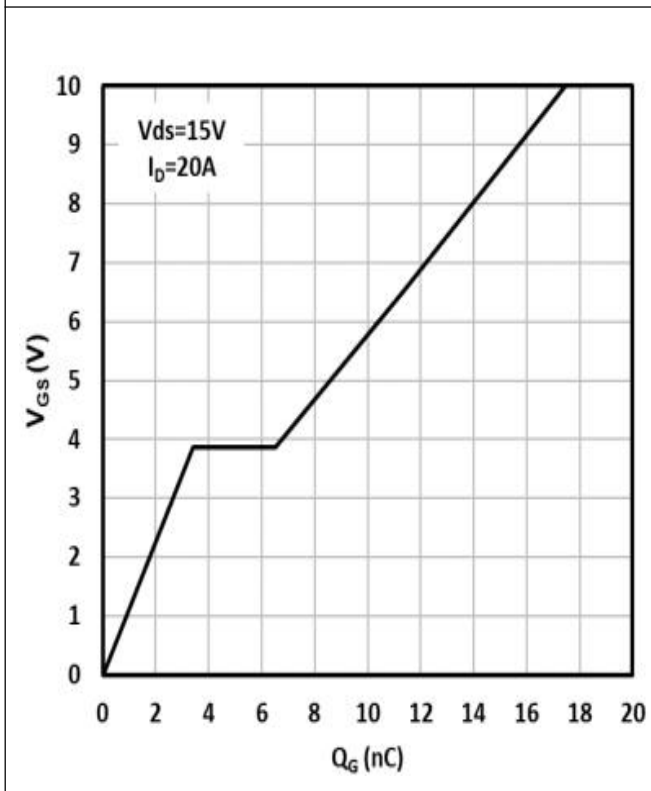


Figure 10: Maximum Drain current vs. Case temperature

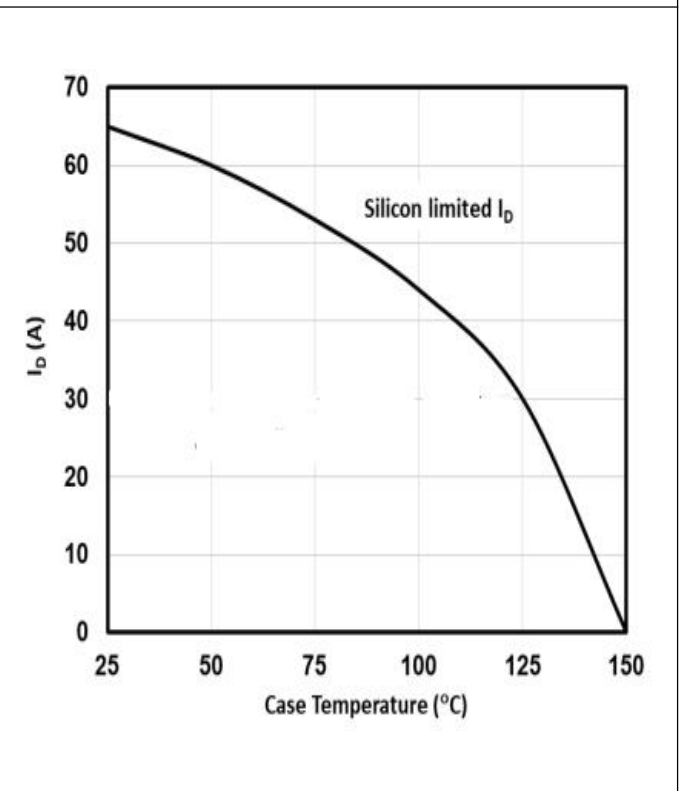


Figure 11: Normalized drain-to-source breakdown vs. temperature

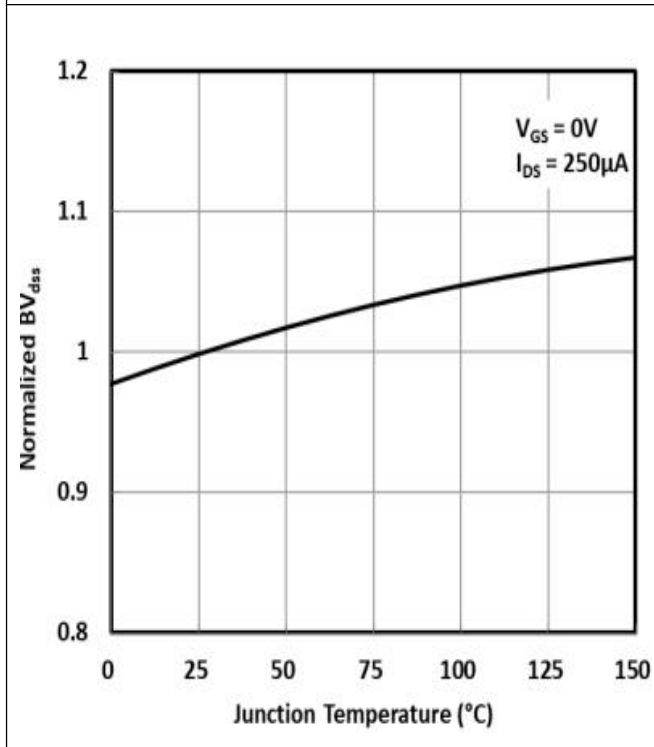


Figure 12: Drain-to-source leakage current vs. voltage

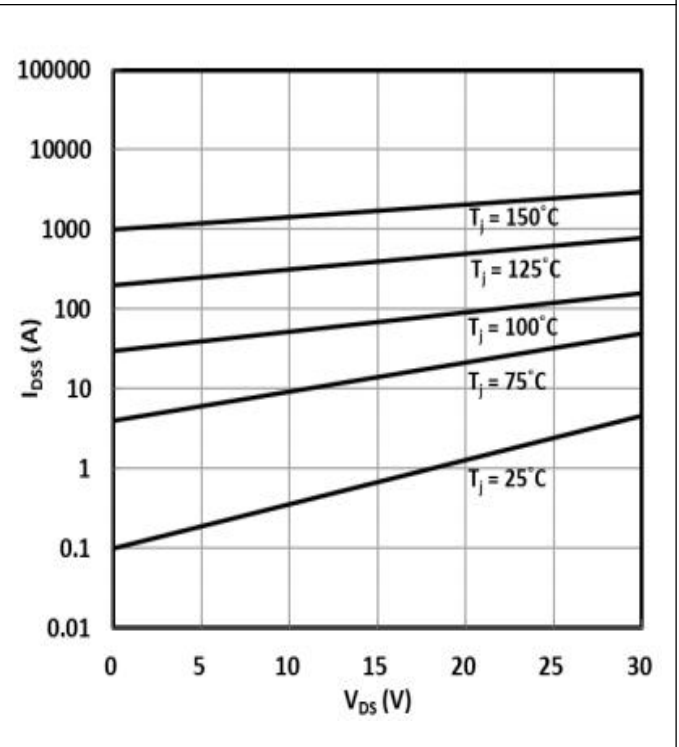


Figure 13: Maximum Drain current vs. Ambient temperature

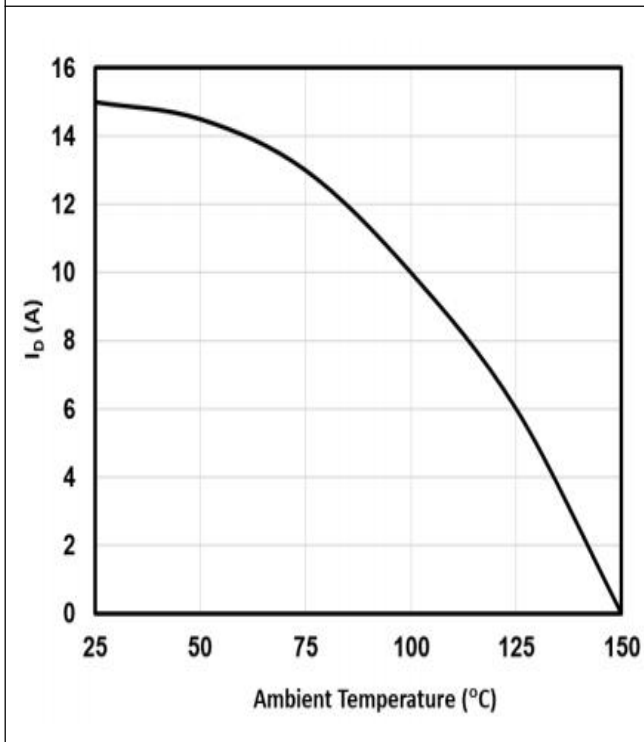
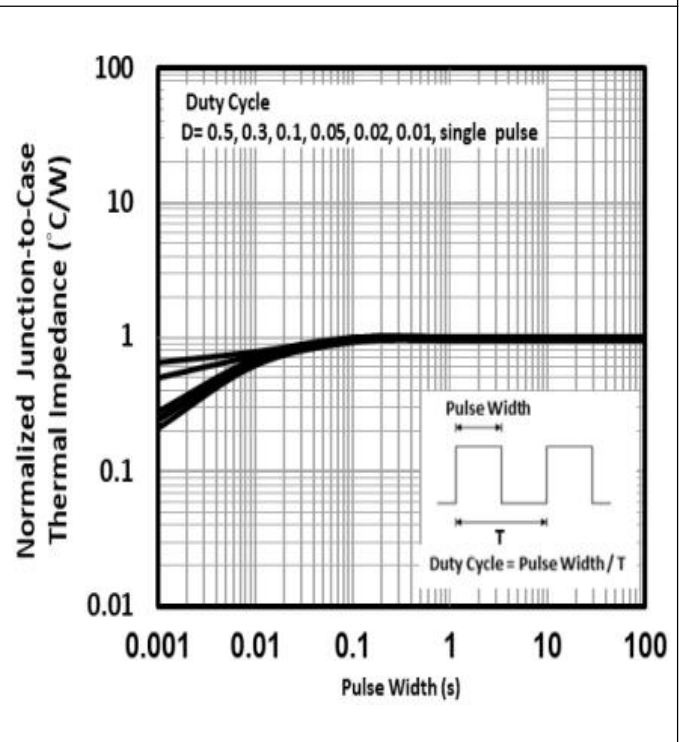
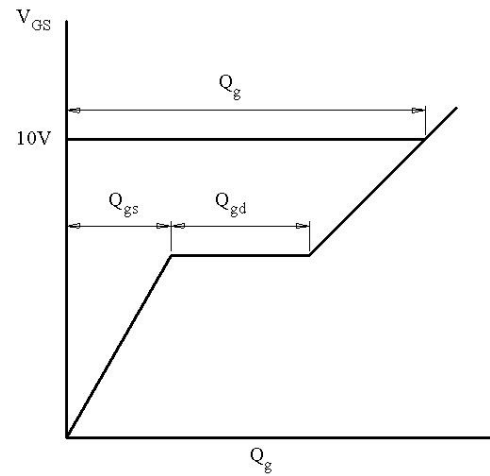
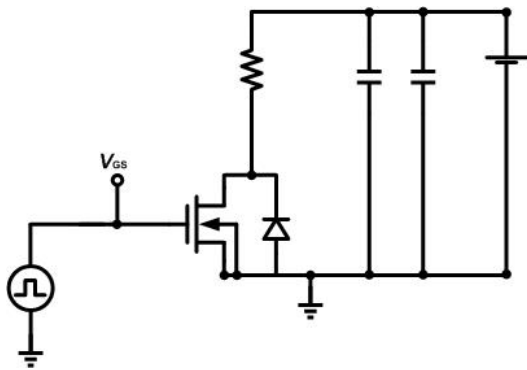
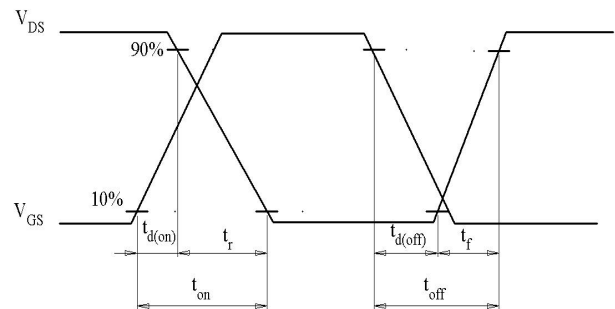
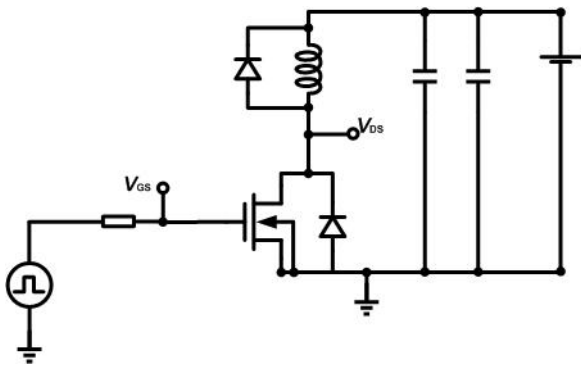
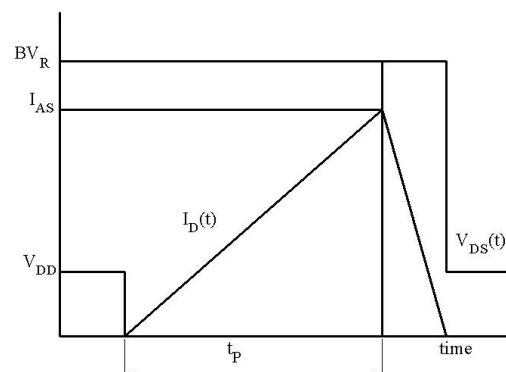
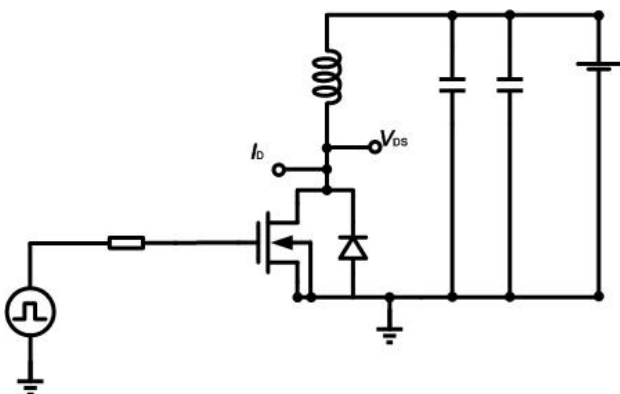
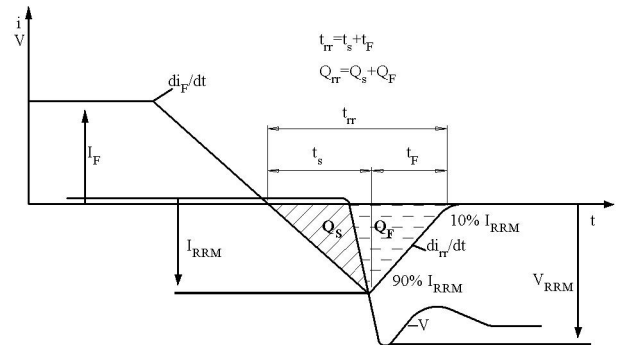
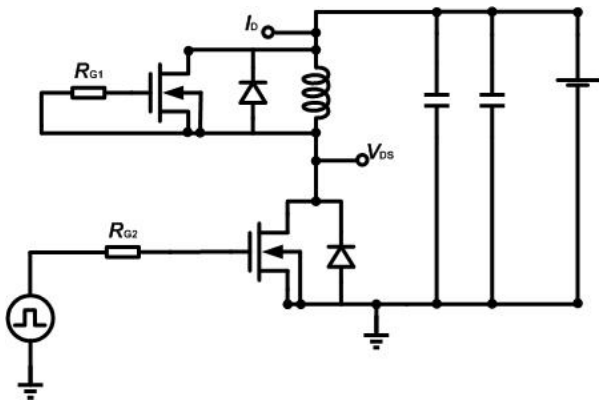


Figure 14: Junction-to-case thermal impedance

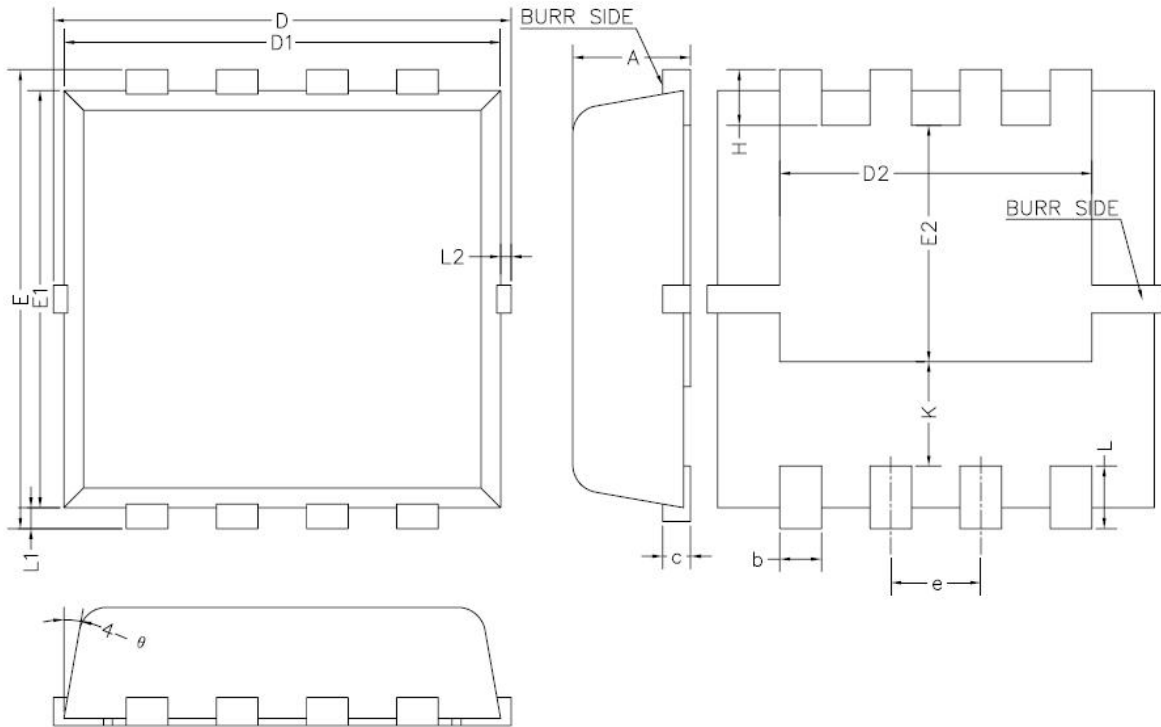


**Test Circuits**
**1. Gate Charge Test Circuit & Waveform**

**2. Switch Time Test Circuit**

**3. Unclamped Inductive Switching Test Circuit & Waveforms**


**4. Test Circuit and Waveform for Diode Characteristics**





**Mechanical Dimensions**
**PDFN3.3\*3.3**
**Unit: mm**


Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	0.70	0.8	0.9
b	0.25	0.30	0.39
c	0.14	0.15	0.20
D	3.10	3.30	3.50
D1	3.05	3.15	3.25
D2	2.15	2.25	2.35
e	0.55	0.65	0.75
E	3.10	3.30	3.50
E1	2.90	3.00	3.10
E2	1.60	1.70	1.80
H	0.25	0.40	0.55
K	0.65	0.75	0.85
L	0.30	0.45	0.60
L1	0.05	0.15	0.25
L2	-	-	0.15
θ	8°	10°	12°



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